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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

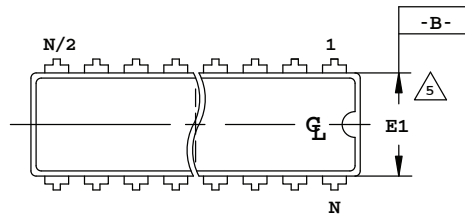
The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

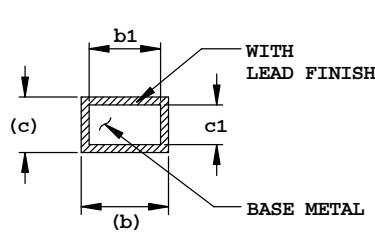
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6100
Total RAM Bits	94208
Number of I/O	224
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec6e-4f484i

20-Pin Plastic DIP Package

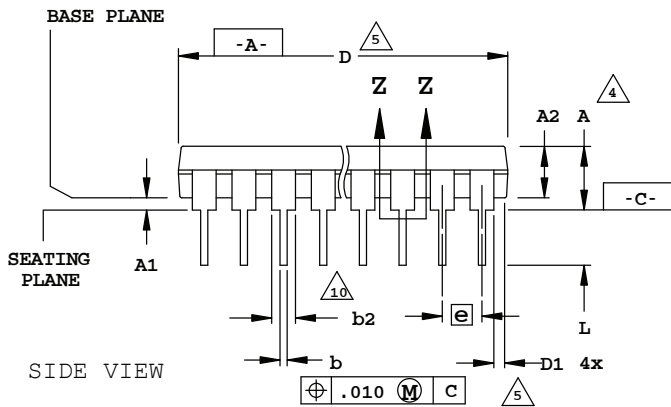
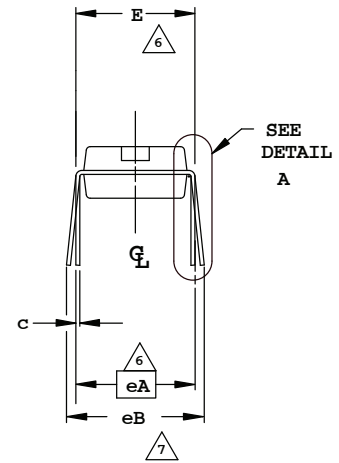
Dimensions in Inches



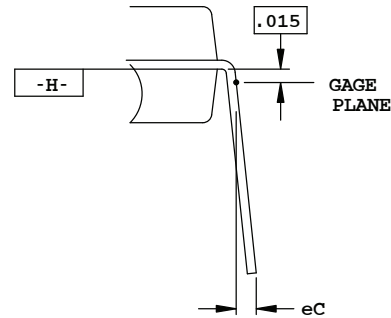
TOP VIEW



SECTION Z-Z



SIDE VIEW



DETAIL A

NOTES:

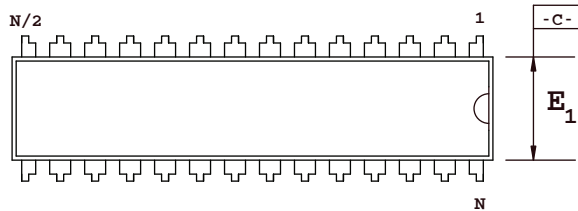
1. CONTROLLING DIMENSION: INCH.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR PROTRUSIONS TO BE .005 MINIMUM.
4. DIMENSIONS A, A1 & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3.
5. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010
6. E AND eA MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM -C-
7. eB AND eC ARE MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
8. N IS THE MAXIMUM NUMBER OF LEAD POSITIONS.
9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
10. b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
11. DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD, WHERE LEAD EXITS BODY

N = 20				
SYMBOL	INCHES			NOTES
	MIN.	NOM.	MAX.	
A	-	-	.210	4
A1	.015	-	-	4
A2	.115	.130	.195	
b	.014	.018	.022	
b1	.014	.018	.020	
b2	.045	.060	.070	10
C	.008	.010	.014	
C1	.008	.010	.011	
D	.980	1.030	1.060	5
D1	.005	-	-	5
E	.300	.310	.325	6
E1	.240	.250	.280	5
e	.100 BSC			
eA	.300 BSC			6
eB	-	-	.430	7
eC	.000	-	.060	7
L	.115	.130	.150	4

28-Pin Plastic DIP Package

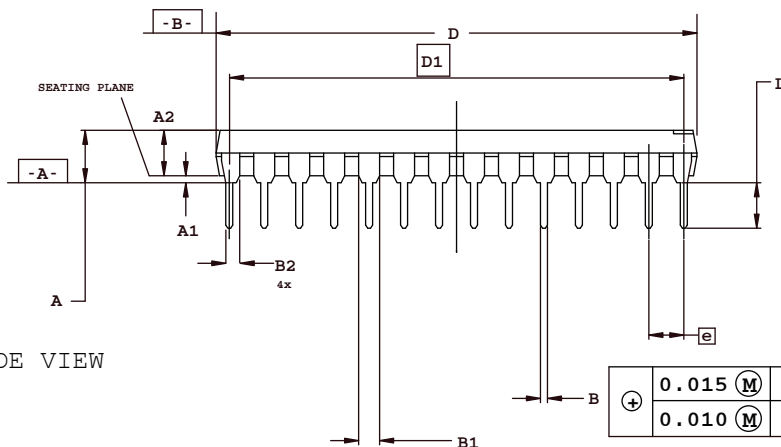
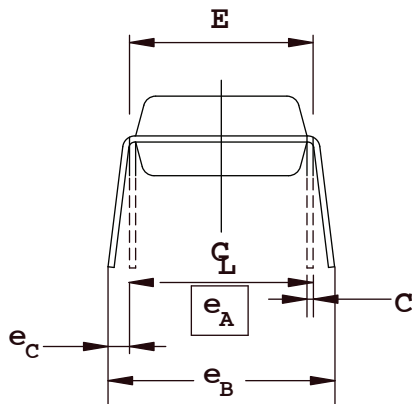
Dimensions in Inches

TOP VIEW



NOTE:

- 1 CONTROLLING DIMENSION: INCHES
- 2 DIMENSIONING AND TOLERANCING
PER ANSI Y14.5M-1982
- 3 ALL END LEADS IN THIS FAMILY ARE 1/2 LEADS
- 4 DIMENSION A, A1, AND L ARE MEASURED WITH THE
PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-3
- 5 D AND E1 DIMENSIONS DO NOT INCLUDE MOLD
FLASH OR PROTRUSION. MOLD FLASH AND
PROTRUSION SHALL NOT EXCEED 0.010
- 6 E AND eA MEASURED WITH THE LEADS
CONSTRAINED TO BE PERPENDICULAR TO PLANE A
- 7 eB AND eC ARE MEASURED AT THE LEAD TIPS
WITH THE LEADS UNCONSTRAINED. eC MUST BE
ZERO OR GREATER
- 8 N IS THE NUMBER OF TERMINAL POSITIONS
- 9 B1 AND B2 MAXIMUM DIMENSIONS DO NOT INCLUDE
DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS
SHALL NOT EXCEED 0.010



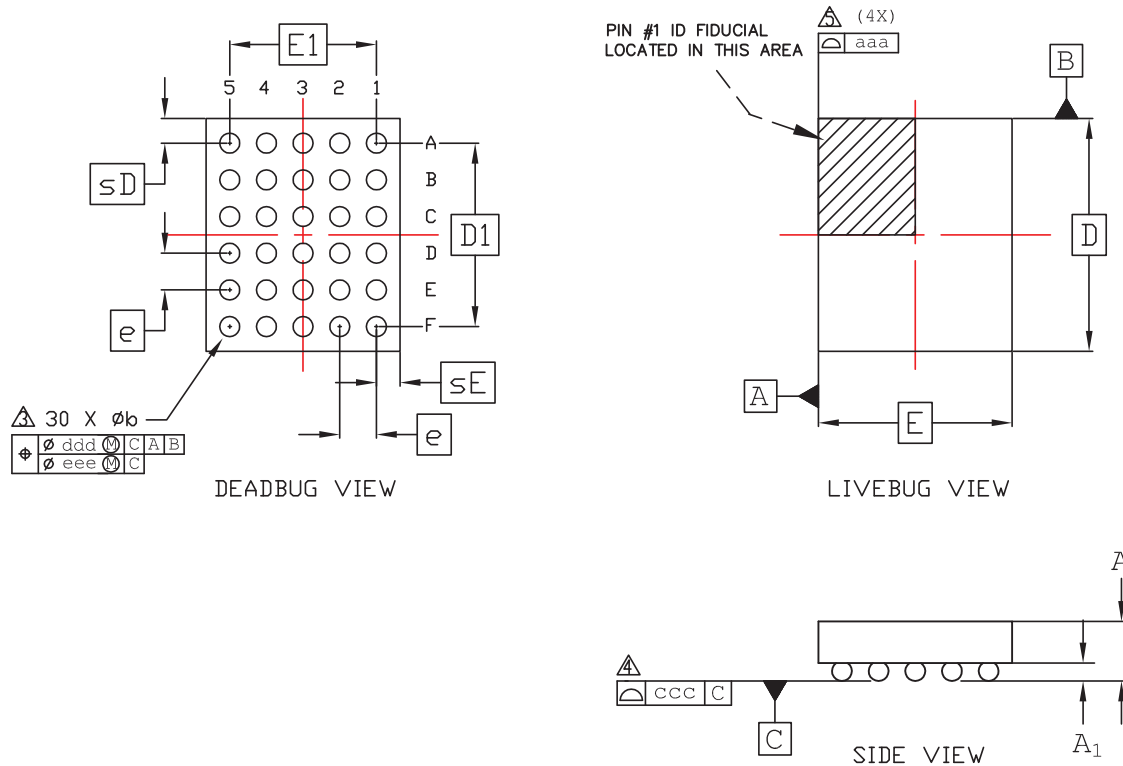
SIDE VIEW

SYMBOL	INCHES		
	MIN.	NOM.	MAX.
A	-	-	.180
A1	.015	-	-
A2	.120	.135	.150
B	.014	.018	.022
B1	.045	.050	.060
B2	.030	.040	.045
C	.008	.010	.015
D	1.345	1.365	1.385
D1	1.300 BSC		
E	.300	.310	.325
E1	.275	.285	.295
e	.100 BSC		
eA	.300 BSC		
eB	-	-	.430
eC	.000	-	.060
L	.110	.130	.150
N	28		

+	0.015 (M)	A	B	C
	0.010 (M)	A		

30-Ball WLSC Package

Dimensions in Millimeters



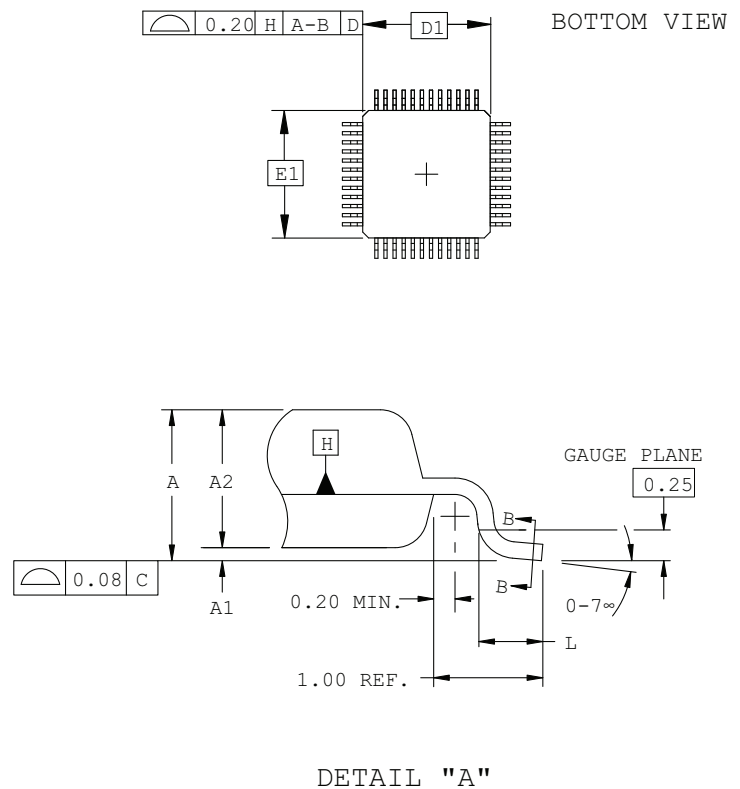
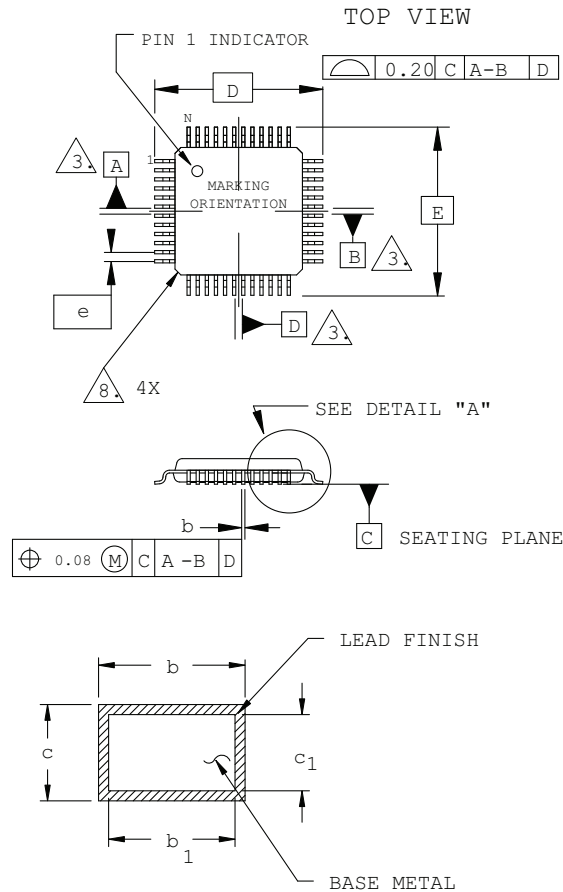
Notes:

- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M - 1994.
 - 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- Δ DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- Δ PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- Δ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom.	Max.
A	-	-	0.600
A1	0.140	-	-
b	0.230	0.260	0.290
D	2.537 BSC		
E	2.114 BSC		
D1	2.00 BSC		
E1	1.60 BSC		
e	0.40 BSC		
sD	-	0.26	-
sE	-	0.27	-
aaa	0.030		
ccc	0.050		
ddd	0.015		
eee	0.050		

48-Pin TQFP Package (1.4 mm thick)

Dimensions in Millimeters



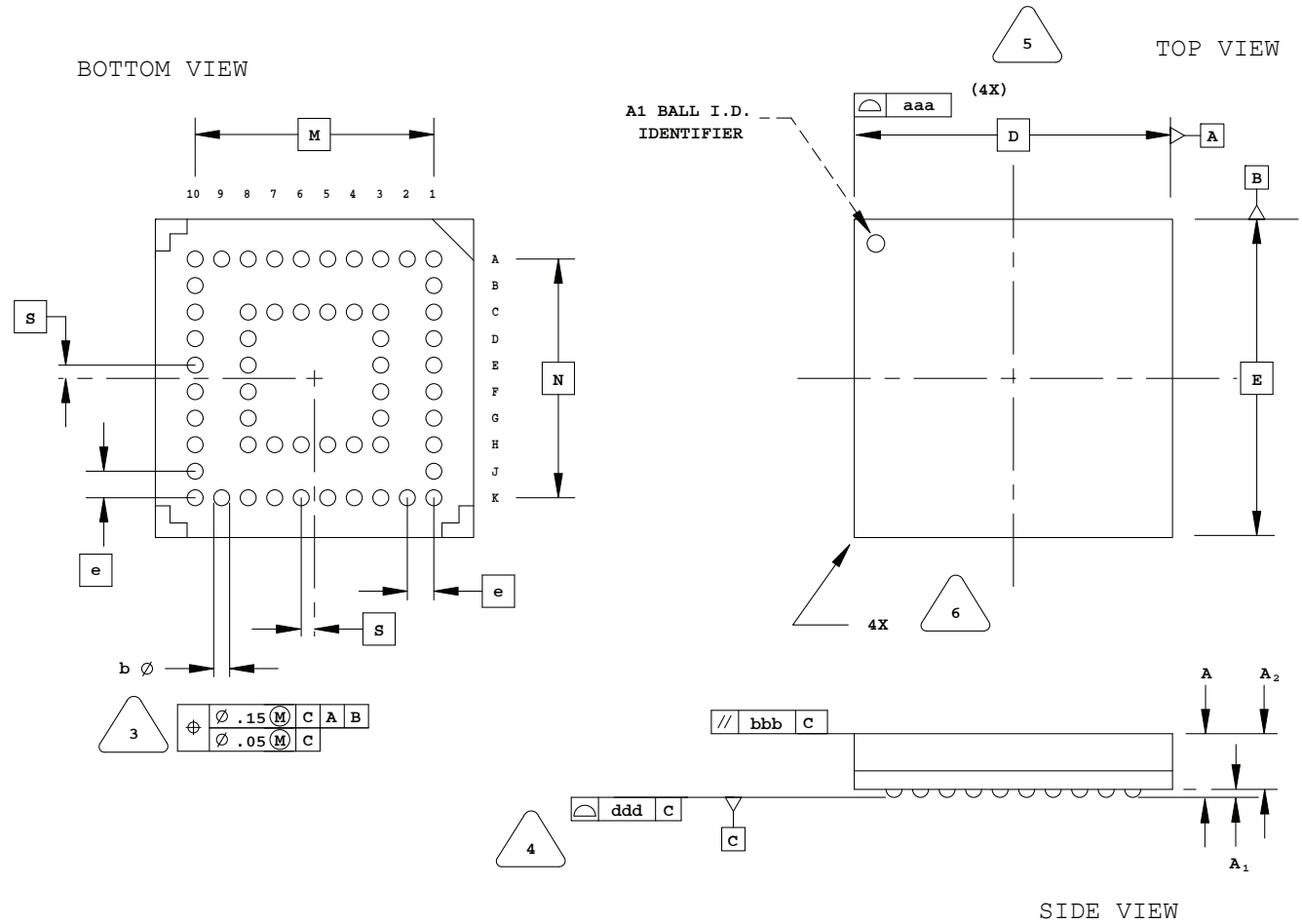
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D	9.00 BSC		
D1	7.00 BSC		
E	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
N	48		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

56-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

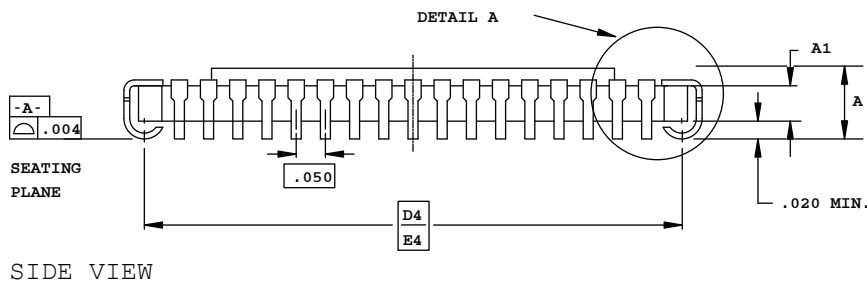
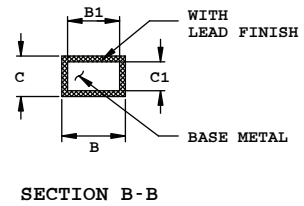
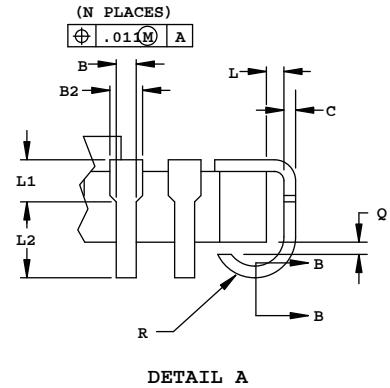
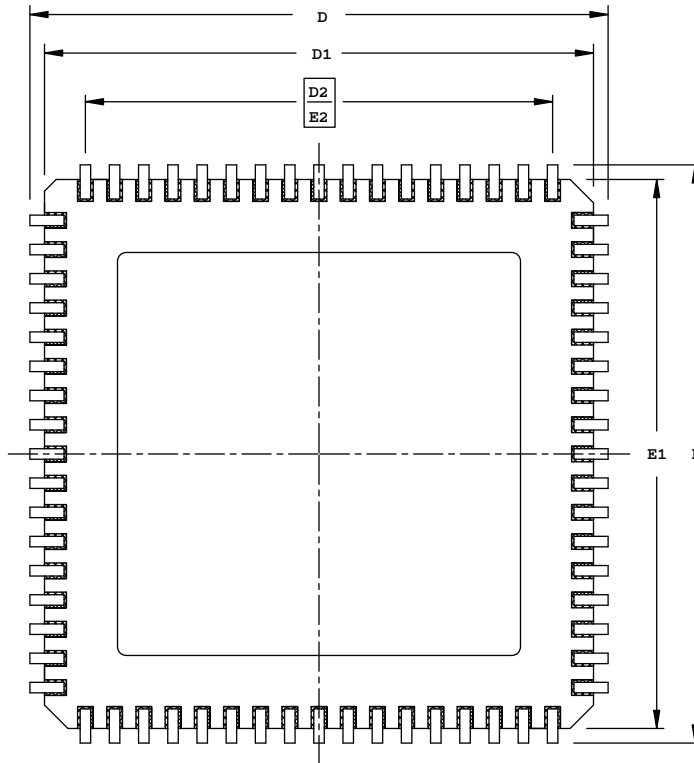
3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.10	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	6.00 BSC		
M/N	4.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

68-Pin JLCC Package

Dimensions in Inches

BOTTOM VIEW



SIDE VIEW

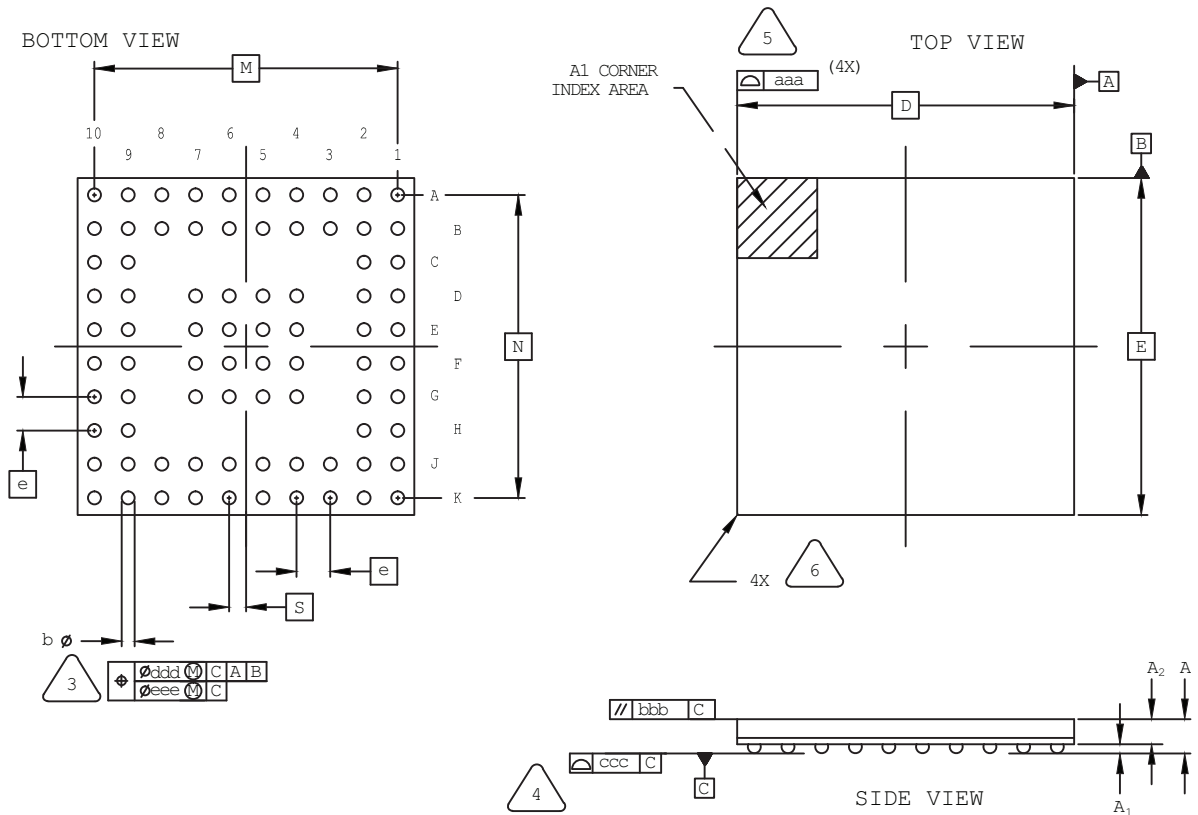
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN INCHES.
3. CORNER CHAMFERS AND/OR NOTCHES ARE OPTIONAL.

SYMBOL	INCHES		
	MIN.		MAX.
A	.115	-	.190
A1	.080 REF		
B	.013	-	.023
B1	.013	-	.020
B2	.022	-	.035
C	.007	-	.013
C1	.007	-	.010
D/E	.975	.990	1.000
D1/E1	.920	-	.960
D2/E2	.800 BSC		
D4/E4	.930 BSC		
L	.005	-	-
L1	.020	-	-
L2	.025	-	-
Q	.003	-	-
R	.020	-	.040
N	68		

80-Ball ctfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

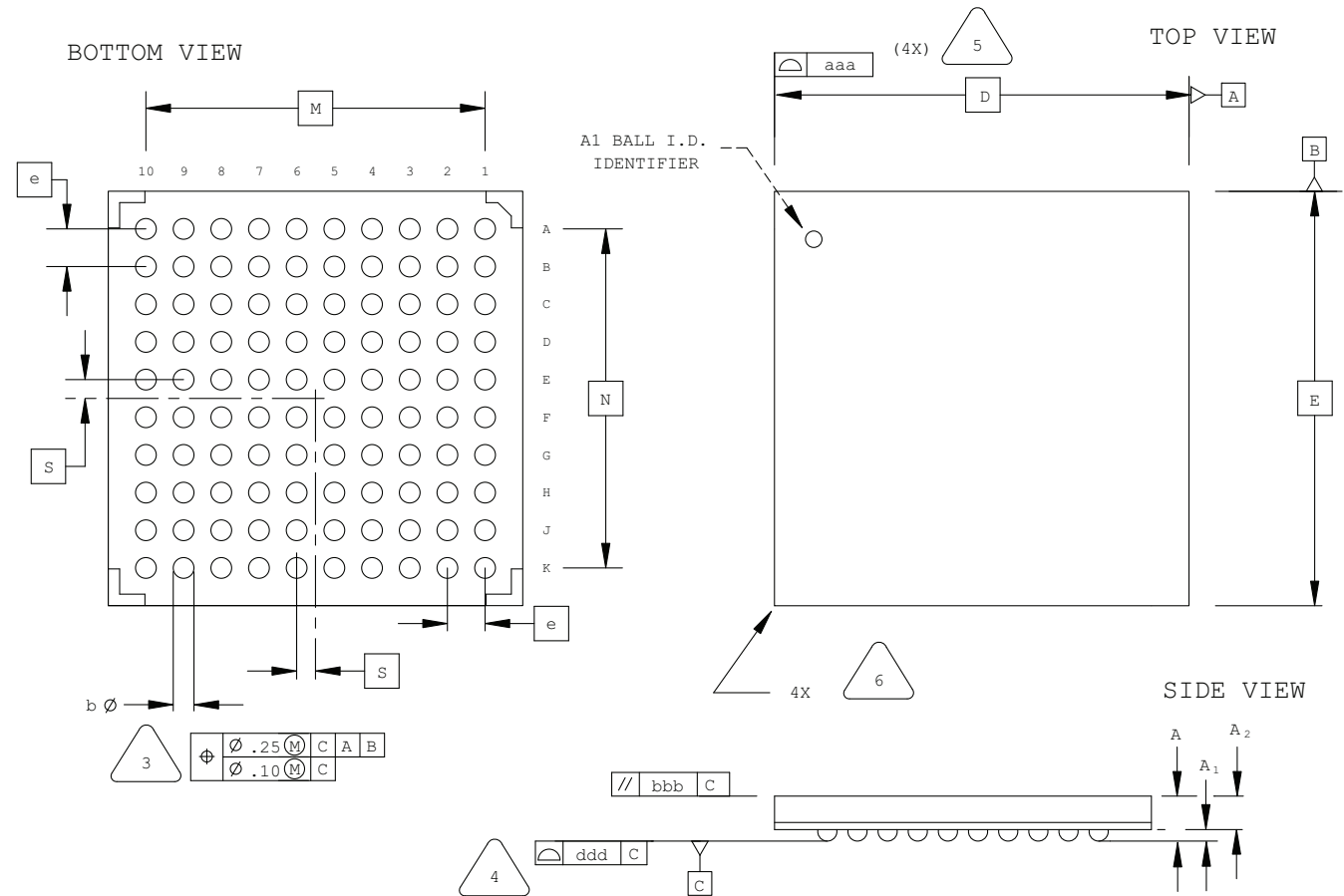
1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.

- 3** DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].
- 4** PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5** BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- 6** EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	–	–	1.00
A1	0.11	–	–
A2	0.61	–	–
D/E	6.50 BSC		
M/N	5.85 BSC		
S	0.325 BSC		
b	0.20	0.25	0.30
e	0.65 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		

100-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

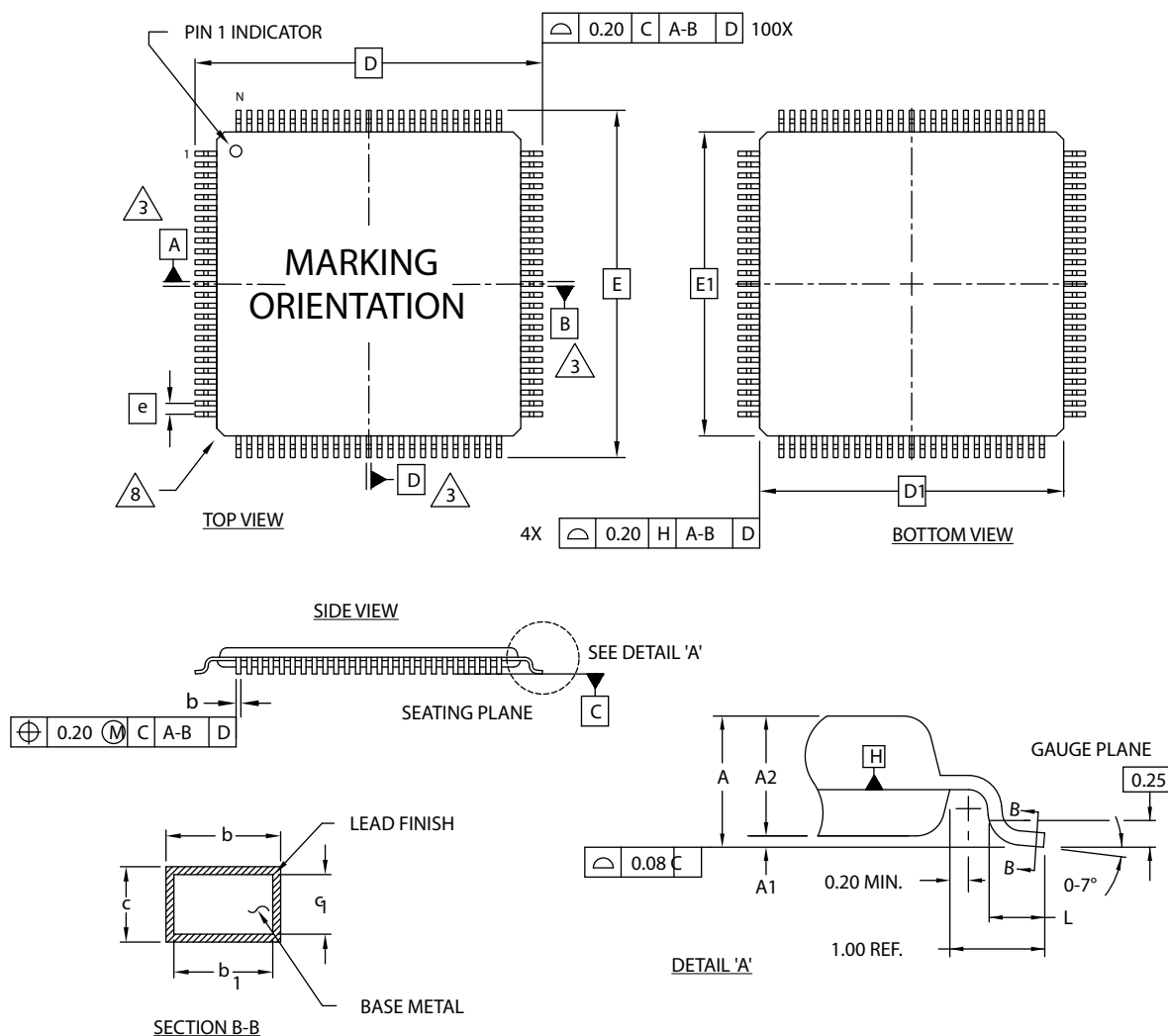
- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.

- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.50	1.70
A1	0.30	0.50	0.70
A2	1.10 REF		
D/E	11.00 BSC		
M/N	9.00 BSC		
S	0.50 BSC		
b	0.40	0.55	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

100-Pin VQFP Package Option 2: iCE40

Dimensions in Millimeters



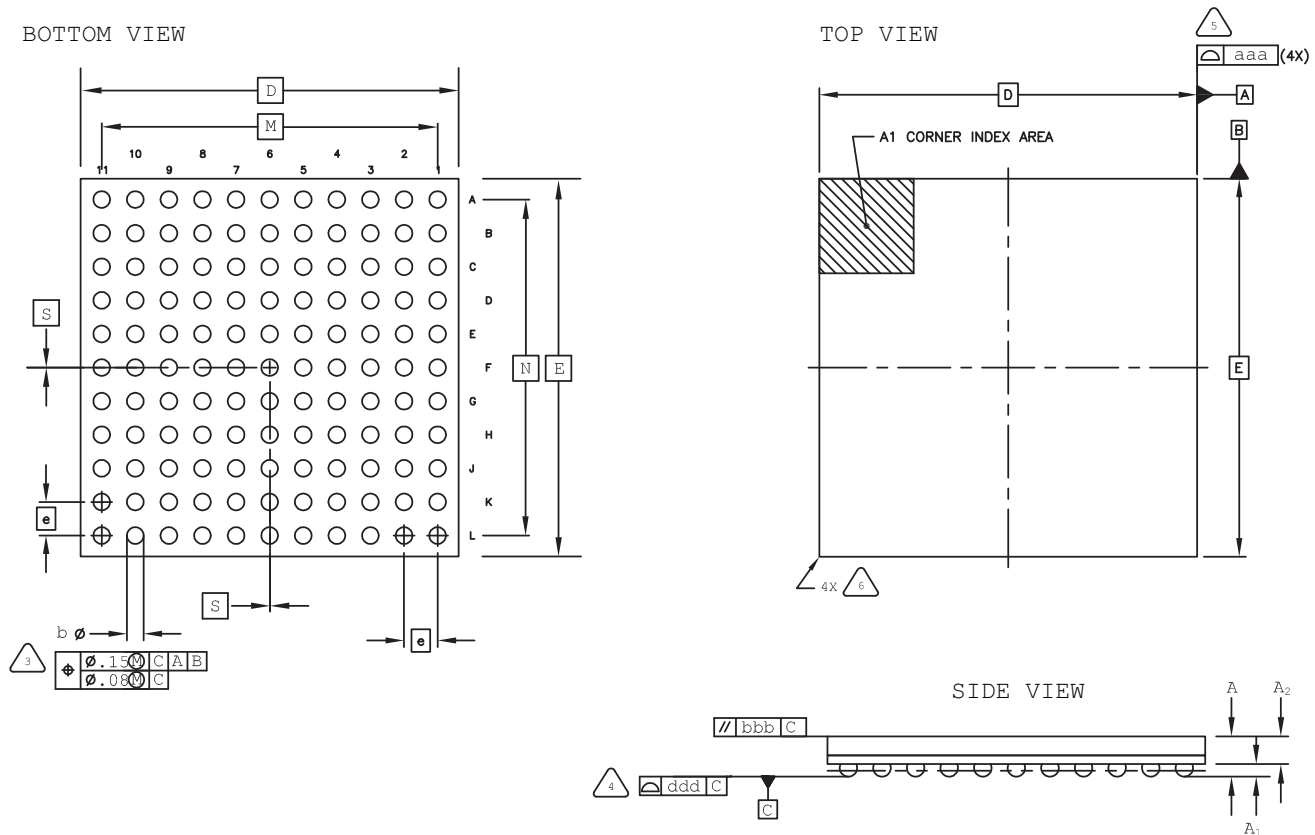
NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 - 1982.
2. ALL DIMENSIONS ARE IN MILLIMETERS.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
6. SECTION B-B:
THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
8. EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.05	-	0.15
A2	0.95	1.00	1.05
D	16.00 BSC		
D1	14.00 BSC		
E	16.00 BSC		
E1	14.00 BSC		
L	0.45	0.60	0.75
N	100		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
c	0.09	0.15	0.20
c1	0.09	0.13	0.16

121-Ball caBGA Package (9x9 mm Body)

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

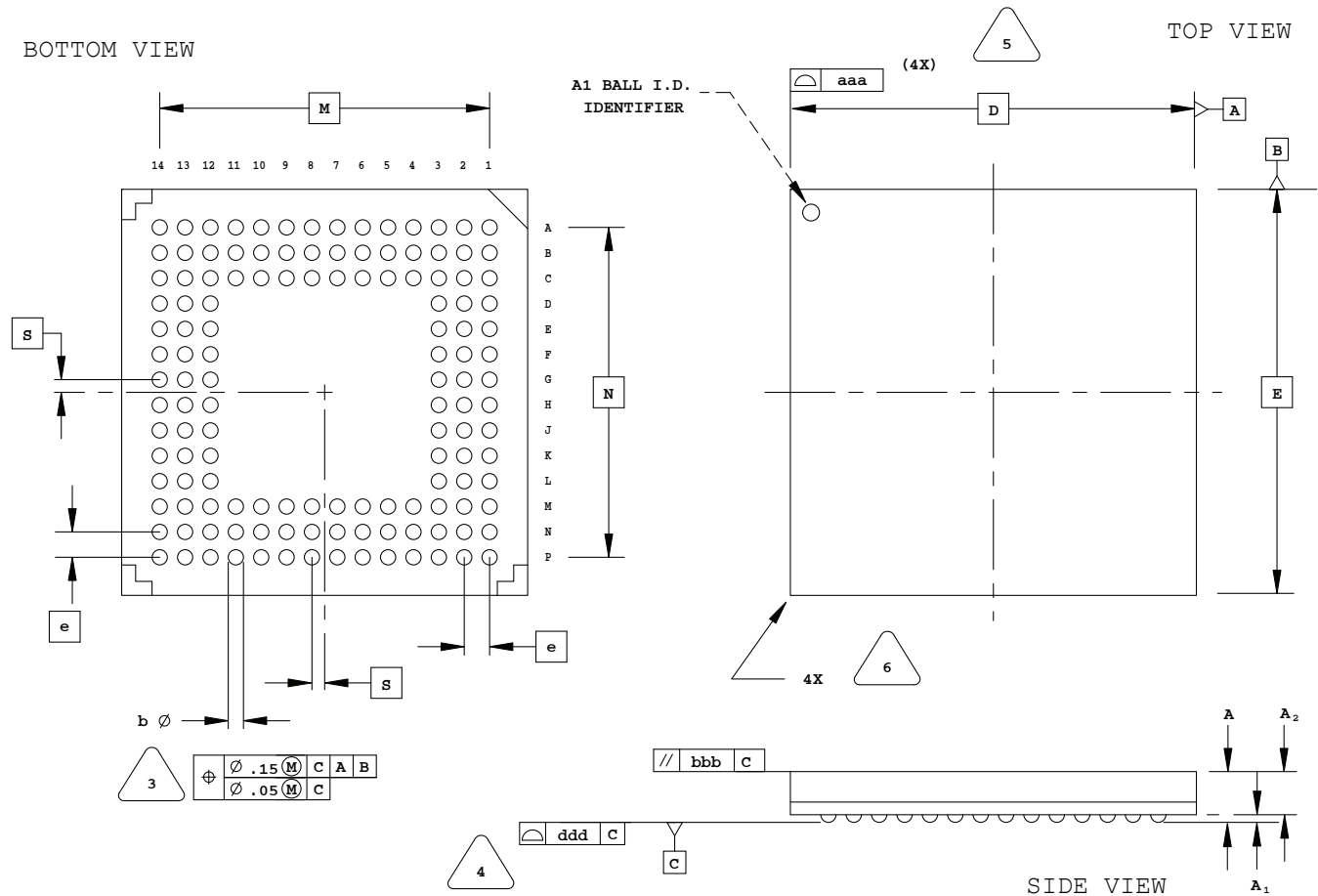


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.10
A1	0.15	-	-
A2	0.55	-	-
D/E	9.00 BSC		
M/N	8.00 BSC		
S	0.00 BSC		
b	0.30	0.40	0.50
e	0.80 BSC		
aaa	0.15		
bbb	0.20		
ddd	0.10		

132-Ball csBGA Package Option 1: MachXO2, MachXO, LatticeXP2™

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

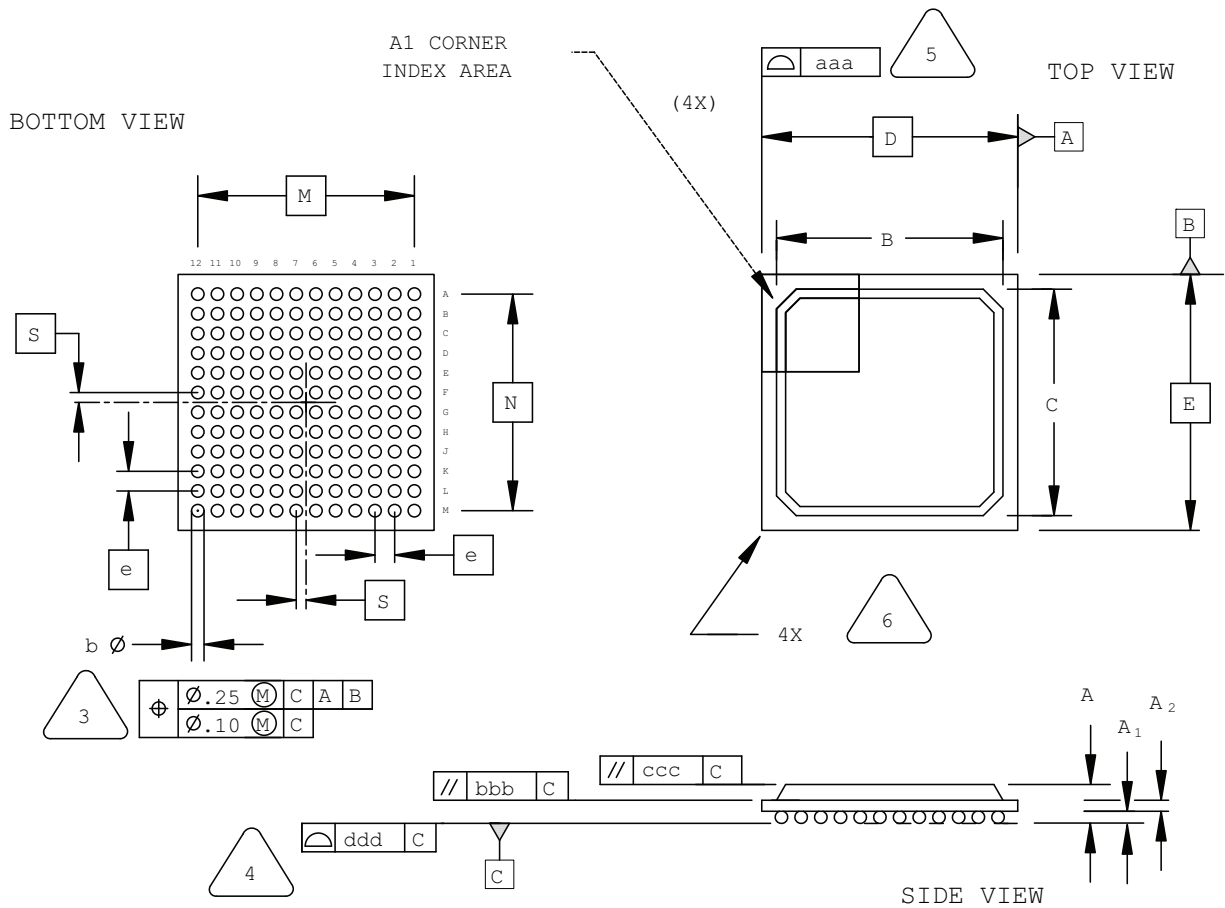


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	0.90	1.23	1.35
A1	0.15	-	-
A2	-	-	1.10
D/E	8.00 BSC		
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.08

144-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]



PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

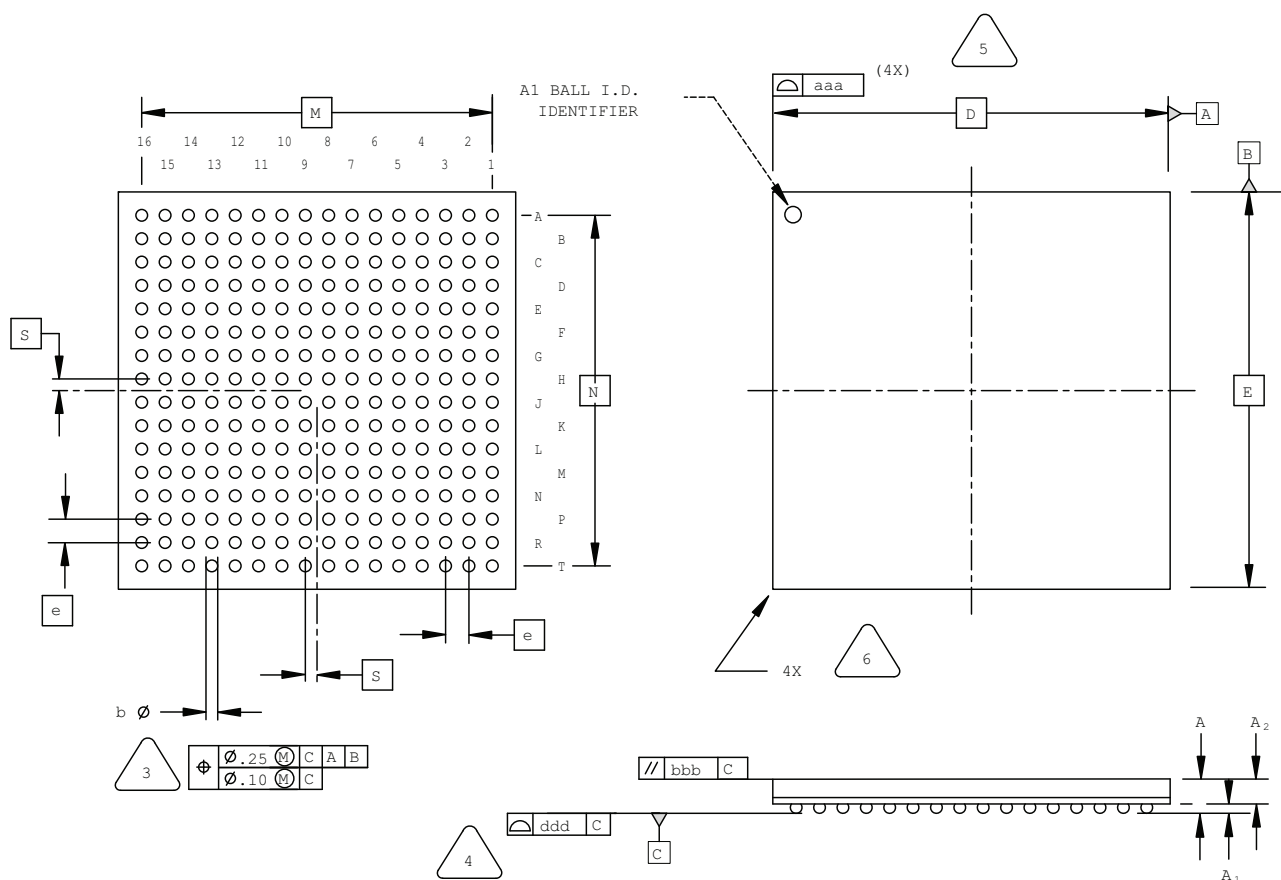


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	11.00	11.60	12.20
D/E	13.00 BSC		
M/N	11.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES
PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE
MAXIMUM SOLDER BALL DIAMETER,
PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED
TO EACH SIDE OF THE PACKAGE BODY.

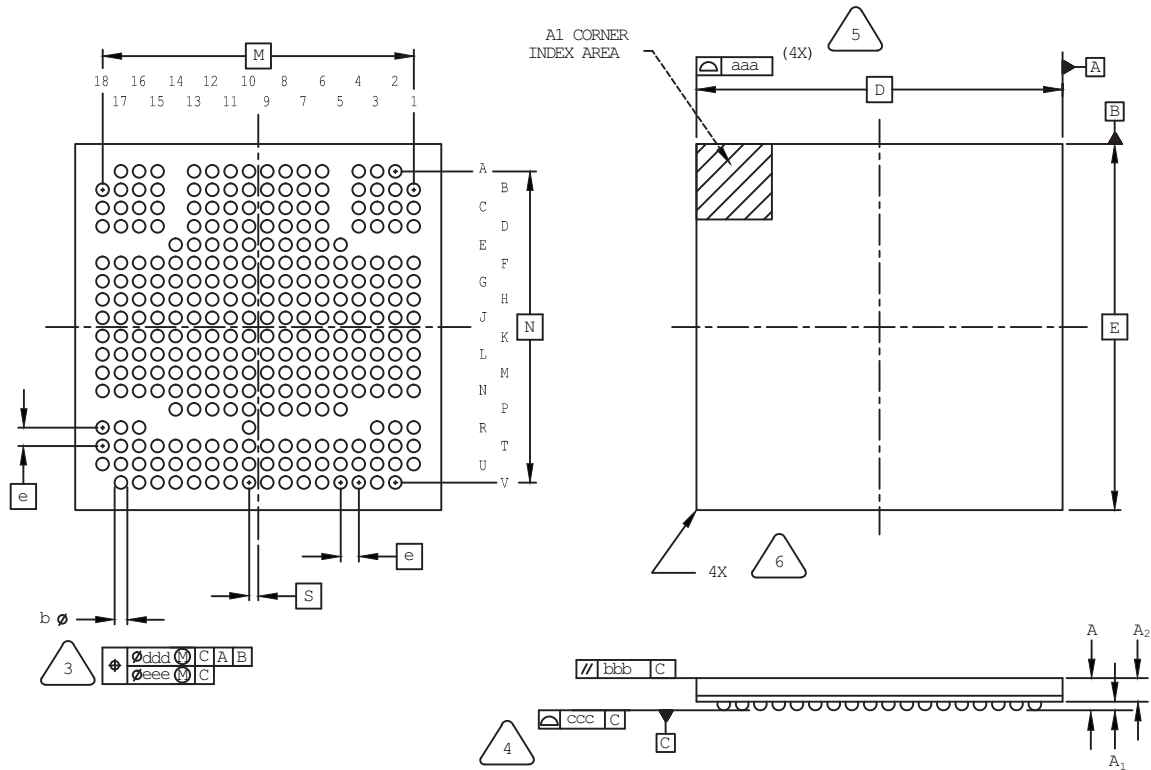


EXACT SHAPE AND SIZE OF THIS FEATURE
IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.25	1.40	1.55
A1	0.30	-	-
A2	-	-	1.25
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.12

285-Ball csfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C .



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

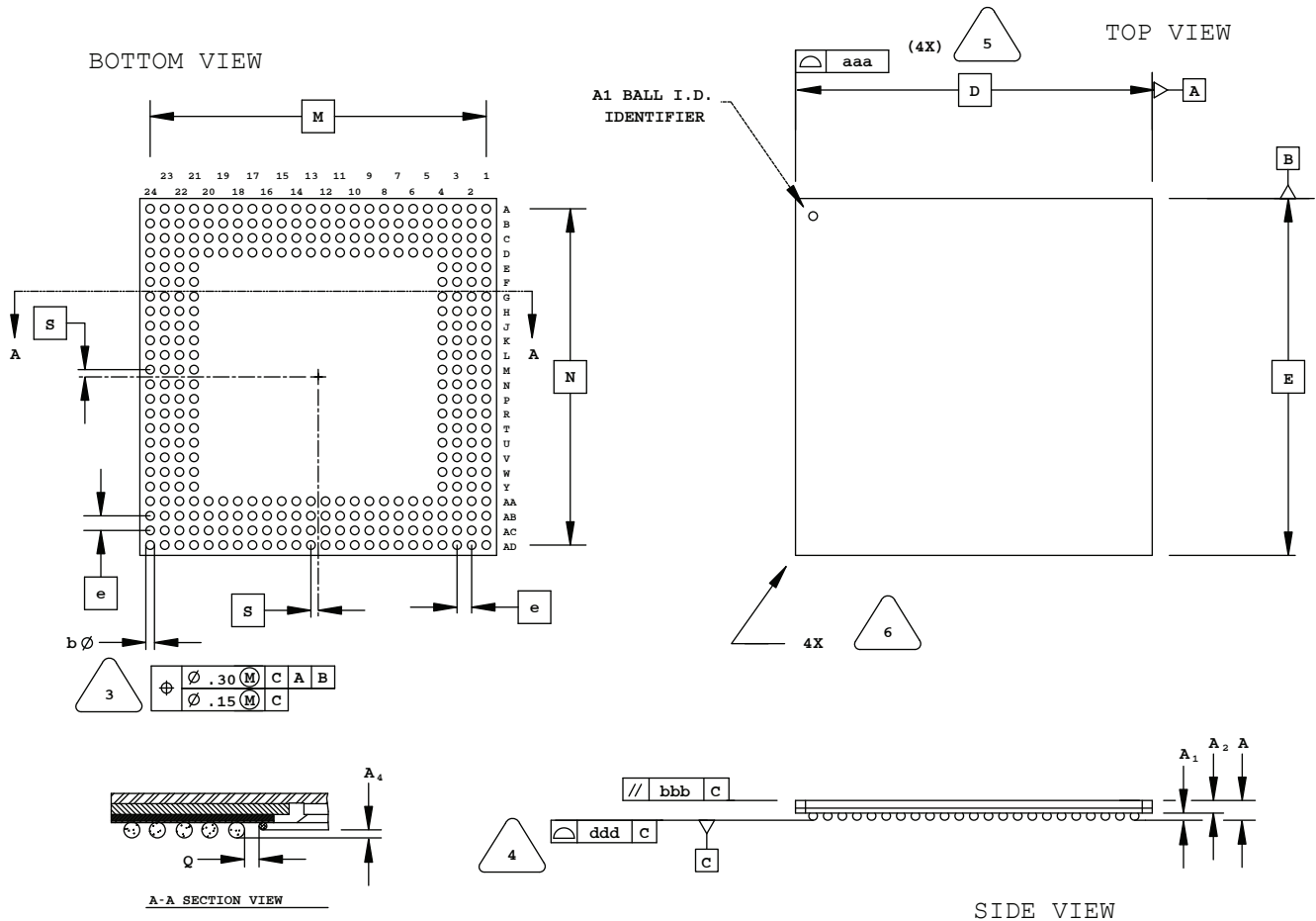


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.30
A1	0.15	-	-
A2	-	-	1.00
D/E	10.00 BSC		
M/N	8.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		

320-Ball SBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**



PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

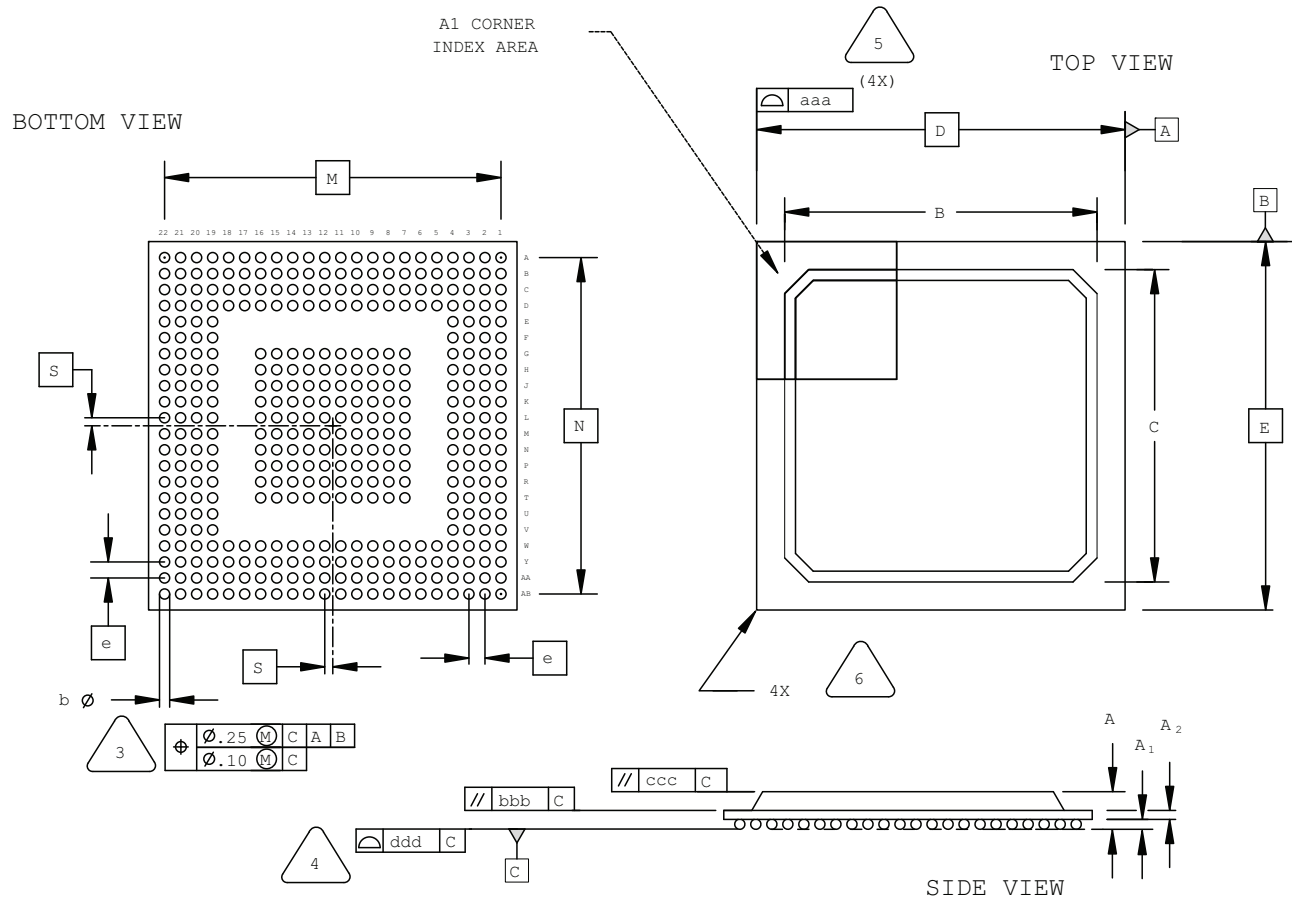


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	31.00 BSC		
M/N	29.21 BSC		
S	0.635 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20

388-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \boxed{C}



PRIMARY DATUM \boxed{C} AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

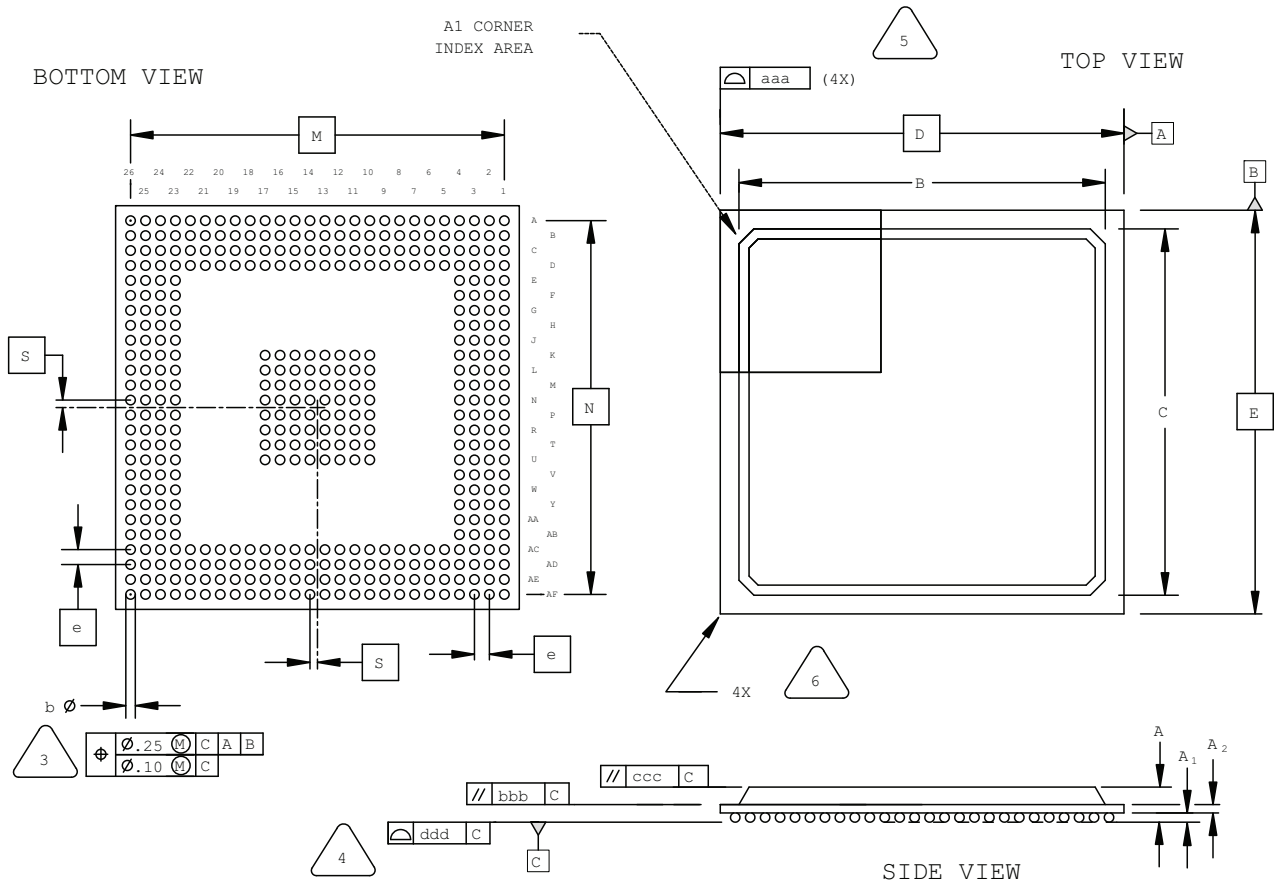


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	19.30	19.80	20.30
D/E	23.00 BSC		
M/N	21.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

416-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.

3. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]

4. PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

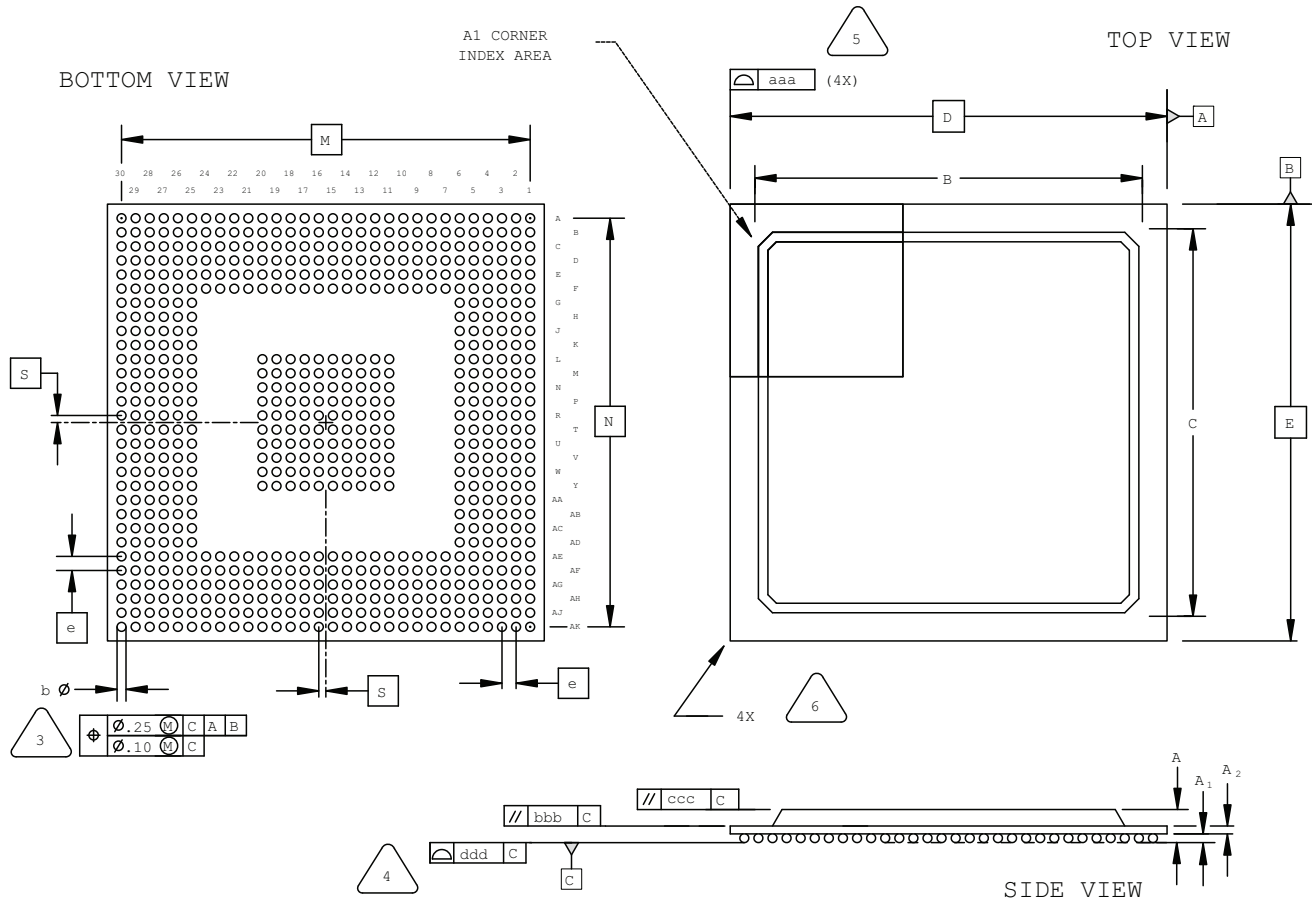
5. BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

6. EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	23.80	24.80	25.80
D/E	27.00 BSC		
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

676-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

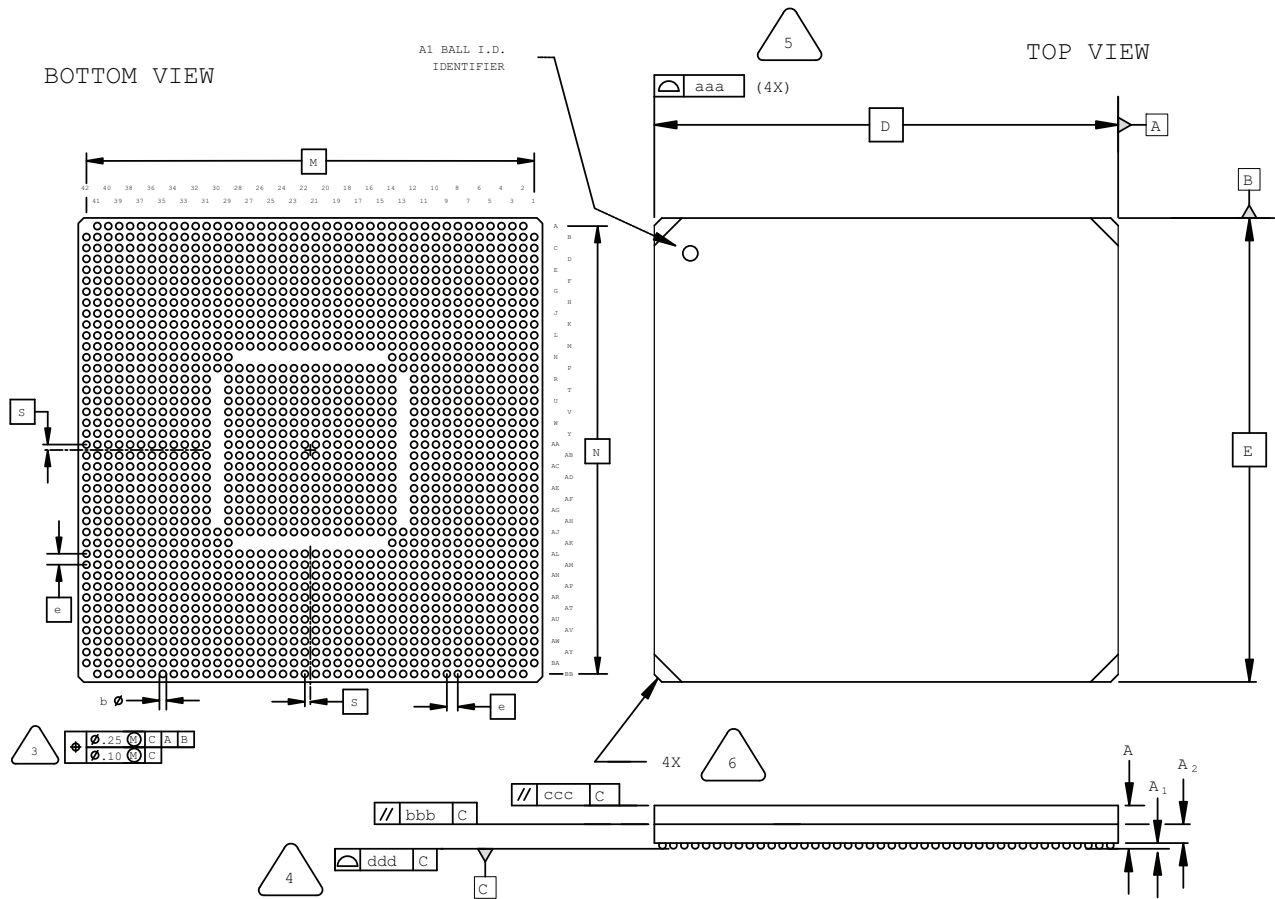


EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	1.70	2.15	2.60
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	25.80	27.55	29.30
D/E	31.00 BSC		
M/N	29.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

1704-Ball Ceramic fcBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM **C**.

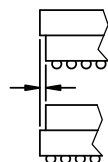


PRIMARY DATUM **C** AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY. PACKAGE BODY INCLUDES SUBSTRATE AND LID.

MAXIMUM OFFSET: 0.20 mm



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	4.30	4.80	5.30
A1	0.30	0.50	0.70
A2	1.30	1.60	1.90
D/E	42.50 BSC		
M/N	41.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20

Date	Version	Change Summary
May 2009	02.0	Added new 256-ball caBGA and 256-ball ftBGA (Option A) packages.
April 2009	01.9	Added 24-pin QFNS package diagram. Removed discontinued and obsolete packages (16 SOIC, 20 SOIC, 24 SOIC, 28 SOIC, 16 PDIP, 240 MQFP, 269 fcBGA, 304 MQFP, 600 SBGA).
December 2008	01.8	Added 32-pin QFNS, 48-pin QFNS and 64-pin QFNS package diagrams.
November 2008	01.7	Added 64-ball ucBGA and 132-ball ucBGA package diagrams.
April 2008	01.6	Added 64-ball csBGA and 144-ball csBGA package diagrams.
November 2007	01.5	Added 1152-ball fpBGA package diagram.
October 2007	01.4	Revised 1036 ftSBGA package diagram. Removed 1036 fpSBGA.
June 2007	01.3	Added 1036 ftSBGA package diagram.
February 2007	01.2	Revised 1704 fcBGA package drawing: removed lid dimension, clarified package body dimension as the combination of substrate and lid.
January 2007	01.1	Added Marking Orientation text for all TQFP packages (1.0 mm and 1.4 mm thick).
October 2006	01.0	Added 64-pin TQFP and 1704-ball fcBGA package diagrams.
—	—	Previous Lattice releases.